

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10779397
<b>Filing Date:</b>	13-Feb-2004
<b>Title of Invention:</b>	Substrate processing apparatus and substrate processing method
<b>First Named Inventor/Applicant Name:</b>	Naoki Shindo
<b>Filer:</b>	David Tai-Wei Yang/Deanna Fintz
<b>Attorney Docket Number:</b>	199372003910

Filed as Large Entity

### Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>490</b>